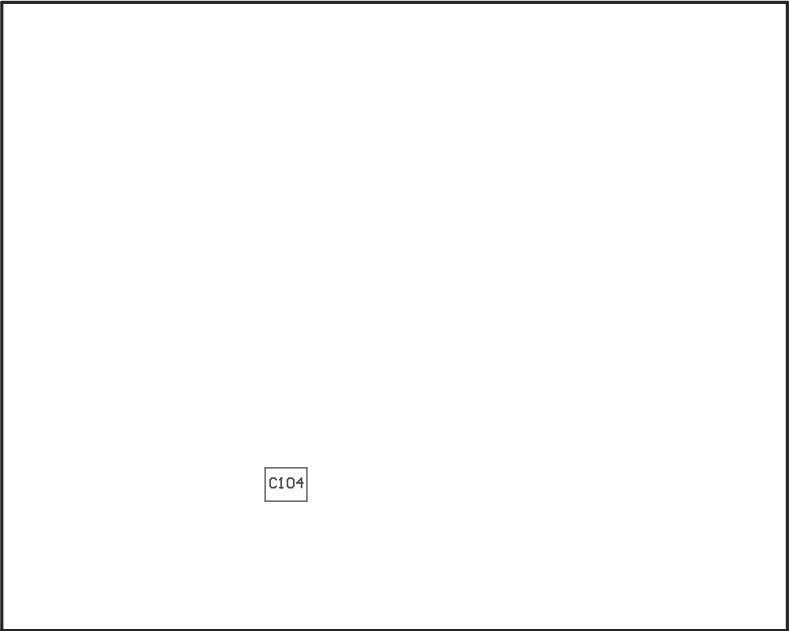


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| PCB VIEWED FROM TOP SIDE | BOARD #: PMP11140 | REV: A | SUN REV: Not In VersionControl |
| | | | |
| PLOT NAME = Top Assembly Drawing | GENERATED : 5/8/2015 10:18:05 AM | TEXAS INSTRUMENTS | |



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

| | | | |
|-------------------------------------|----------------------------------|-------------------|--------------------------------|
| PCB VIEWED FROM BOTTOM SIDE | BOARD #: PMP11140 | REV: A | SUN REV: Not In VersionControl |
| | | | |
| PLOT NAME = Bottom Assembly Drawing | GENERATED : 5/8/2015 10:18:06 AM | TEXAS INSTRUMENTS | |

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